

ABSTRACT

[0021] A process for recovering a solder contaminant from a substrate surface with a wick structure comprising a plurality of heat conductive metal strands and a desoldering flux comprising a mixture of a first component of a partially polymerized rosin having a melting point of at least 98°C, a second component which is present in the desoldering flux formulation in an amount which is no more than the amount of the first component and comprises an ester of a polyhydric alcohol and benzoic acid, and a third component, which is present in an amount which is less than the amount of the second component, and comprises an aliphatic dicarboxylic acid. The solder contaminant is contacted with the wick structure in the presence of the desoldering flux and the wick structure and the solder contaminant are heated to melt the solder contaminant to cause the melted solder to flow into the wick structure in contact with the heat conductive metal strands. The wick structure containing the solder contaminant is withdrawn from the substrate surface.